

L Number	Hits	Search Text	DB	Time stamp
1	38	(koji near2 egashira).in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 14:53
3	41	((yuji near2 kamikawa).in.) and (fan or plane or planar)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 14:58
2	214	(yuji near2 kamikawa).in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 14:58
5	86	((yuji near2 kamikawa).in.) and nozzle	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 14:58
-	6085	(134/198,199,200,902.ccls. or 216/2,92.ccls.) or 156/345.21,345.51,345.54,345.55.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 09:58
-	297	((134/198,199,200,902.ccls. or 216/2,92.ccls.) or 156/345.21,345.51,345.54,345.55.ccls.) and @pd>20040128	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 09:59
-	246	((134/198,199,200,902.ccls. or 216/2,92.ccls.) or 156/345.21,345.51,345.54,345.55.ccls.) and @pd>20040128) and (semiconductor or wafer or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 09:59
-	54	((134/198,199,200,902.ccls. or 216/2,92.ccls.) or 156/345.21,345.51,345.54,345.55.ccls.) and @pd>20040128) and (semiconductor or wafer or substrate)) and (spray\$3) and nozzle	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 09:59